

SHENMAO Introduces SMF-WB02 / SMF-WB51 Water Soluble Flux

SHENMAO SMF-WB02 / SMF-WB51 Water Soluble Flux are made locally in the USA and with the same quality in 7 other world wide locations. It is said their Low Viscosity (easy to apply), High Tackiness (slump resistant), consistent printability for BGA and Micro BGA Ball Assemblies and excellent wash ability after high temperature reflow (255°C and 60 sec over 220°C) create highly reliable Solder Joints with ultra maximized Quality.

A Large Chipset Producer consistently uses SHENMAO SMF-WB02 / SMF-WB51 Water Soluble Flux to achieve ultimately reliable and residue clean Ball Attach connections.

As the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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